

Alvarez
acid), polyacrylic acid, polyacrylamide, aminopolyacrylamide, ammonium polyacrylate, sodium polyacrylate, ammonium polyamide, sodium polyamide, polyglyoxylic acid, etc.; and vinyl polymers such as polyvinyl alcohol, polyvinylpyrrolidone, polyacrolein, etc.--

AS 104060-74
Please delete the paragraph at page 27, lines 14-20, and substitute therefor the following new paragraph:

--In a case where a protective film-forming agent is divided into three portions to be separately in three constituent elements, the metal-polishing liquid material may be composed of, for example, a first constituent element A that comprises an oxidizing agent and a part of the protective film-forming agent, a second constituent element B that comprises an oxidized-metal etchant and another part of the protective film-forming agent, and a third constituent element C that comprises the remaining part of the protective film-forming agent and a dissolution promoter.--

IN THE CLAIMS

Please amend the claims presently in the application as follows:

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4. (Amended) The metal-polishing liquid material according to claim 2, wherein the dissolution promoter is a surfactant. *B*

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6. (Amended) The metal-polishing liquid material according to claim 2, wherein the dissolution promoter is a solvent in which the solubility of the protective film-forming agent is at least 25 g/liter.

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10. (Amended) The metal-polishing liquid material according to claim 2, wherein at least a part of the protective film-forming agent is solid having a mean particle size of at most 100 μ m.

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11. (Amended) The metal-polishing liquid material according to claim 2, further comprising abrasive grains.

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17. (Amended) A method for producing a metal-polishing liquid, comprising a step of diluting the metal-polishing liquid material of claim 2 with a diluent.

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20. (Amended) The method for producing a metal-polishing liquid according to claim 19, wherein the diluent is water or an aqueous diluent solution.

Please add the following new claims to the application:

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--27. The metal-polishing liquid material according to claim 1, wherein the dissolution promoter is a surfactant.

28. The metal-polishing liquid material according to claim 27, wherein the surfactant is at least one of esters,

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7 ethers, polysaccharides, salts of amino acids, polycarboxylic acids, salts of polycarboxylic acids, vinyl polymers, sulfonic acids, sulfonates, and amides.

29. The metal-polishing liquid material according to claim 1, wherein the dissolution promoter is a solvent in which the solubility of the protective film-forming agent is at least 25 g/liter.

30. The metal-polishing liquid material according to claim 29, wherein the solvent is a good solvent for the protective film-forming agent.

31. The metal-polishing liquid material according to claim 29, wherein the solvent is at least one of alcohols, ethers and ketones.

32. The metal-polishing liquid material according to claim 29, wherein the amount of the solvent is smaller than 50 g relative to 100 g of a total amount of the material.

33. The metal-polishing liquid material according to claim 1, wherein at least a part of the protective film-forming agent is solid having a mean particle size of at most 100 μm .

34. The metal-polishing liquid material according to claim 1, further comprising abrasive grains.

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35. A method for producing a metal-polishing liquid, comprising a step of diluting the metal-polishing liquid material of claim 1 with a diluent.

36. The method for producing a metal-polishing liquid according to claim 17, wherein the diluent is water or an aqueous diluent solution.--